

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A heating assembly for a motor vehicle, comprising: [[with]]
at least one PTC element, ~~in particular for a motor vehicle,~~
contact plates configured to make an electrical connection with the at least one PTC
element, and
ribs connected to sides of the contact plates that are opposite to sides of the contact
plates electrically connected to the at least one PTC element,
wherein the at least one PTC element is ~~[[being]]~~ arranged between the contact plates
which ~~serve for making electrical connection,~~
wherein the contact plates and the at least one PTC element are ~~[[being]]~~ bonded by
~~means of~~ an adhesive,
wherein the adhesive has a resistivity of at least 50 ohms \times cm and at most 500 ohms
 \times cm.
2. (Currently Amended) The heating assembly as claimed in claim 1, wherein the adhesive
has a resistivity of at least 80 ohms \times cm and at most 150 ohms \times cm, ~~in particular of 100~~
~~ohms \times cm \pm 10%.~~
3. (Currently Amended) The heating assembly as claimed in claim 1, wherein a ~~[[the]]~~ layer
thickness of the adhesive between the at least one PTC element and one of the ~~[[a]]~~ contact
plates ~~[[plate]]~~ before enforced relaxation is negligible and after enforced relaxation is at
most 0.02 μm , ~~in particular 0.01 μm \pm 10%.~~
4. (Currently Amended) A heating assembly for a motor vehicle, comprising: [[with]]
at least one PTC element, ~~in particular for a motor vehicle,~~
contact plates configured to make an electrical connection with the at least one PTC
element, and

ribs connected to sides of the contact plates that are opposite to sides of the contact plates electrically connected to the at least one PTC element,

wherein the at least one PTC element is ~~is~~ [[being]] arranged between the contact plates ~~which serve for making electrical connection,~~

wherein the contact plates and the PTC element are ~~are~~ [[being]] bonded by ~~means of a~~ solder,

wherein the solder has a resistivity of at least 50 ohms \times cm and at most 500 ohms \times cm.

5. (Currently Amended) The heating assembly as claimed in claim 4, wherein the solder has a resistivity of at least 80 ohms \times cm and at most 150 ohms \times cm, ~~in particular of 100 ohms \times cm \pm 10%.~~

6. (Currently Amended) The heating assembly as claimed in claim 4, wherein a ~~the~~ layer thickness of the solder between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm , ~~in particular 0.01 μm \pm 10%.~~

7. (Withdrawn – Currently Amended) An adhesive or a solder for bonding between a ceramic PTC element and an electrically conducting contact plate, wherein characterized in that the adhesive ~~[[5]]~~ or the solder has a resistivity of at least 50 ohms \times cm and at most 500 ohms \times cm.

8. (Withdrawn – Currently Amended) The heating assembly as claimed in claim 2, wherein a ~~the~~ layer thickness of the adhesive between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm , ~~in particular 0.01 μm \pm 10%.~~

9. (Withdrawn – Currently Amended) The heating assembly as claimed in claim 5, wherein a ~~the~~ layer thickness of the solder between the PTC element and a contact plate before

enforced relaxation is negligible and after enforced relaxation is at most $0.02\text{ }\mu\text{m}$, in particular $0.01\text{ }\mu\text{m} \pm 10\%$.

10. (New) The heating assembly as claimed in claim 2, wherein the adhesive has a resistivity of $100\text{ ohms} \times \text{cm} \pm 10\%$.

11. (New) The heating assembly as claimed in claim 3, wherein the layer thickness of the adhesive between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is $0.01\text{ }\mu\text{m} \pm 10\%$.

12. (New) The heating assembly as claimed in claim 5, wherein the solder has a resistivity of $100\text{ ohms} \times \text{cm} \pm 10\%$.

13. (New) The heating assembly as claimed in claim 6, wherein the layer thickness of the solder between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is $0.01\text{ }\mu\text{m} \pm 10\%$.

14. (New) The heating assembly as claimed in claim 1, wherein a ratio of a resistance of the at least one PTC element to a resistance of the adhesive surrounding the at least one PTC element is between about 4 and 40.

15. (New) The heating assembly as claimed in claim 4, wherein a ratio of a resistance of the at least one PTC element to a resistance of the solder surrounding the at least one PTC element is between about 4 and 40.

16. (New) The heating assembly as claimed in claim 1, wherein a ratio of an output of the PTC element with the adhesive without enforced relaxation to an output of the PTC element in connection with the adhesive with enforced relaxation is between about 1.2 and 1.02.

17. (New) The heating assembly as claimed in claim 4, wherein a ratio of an output of the PTC element with the solder without enforced relaxation to an output of the PTC element in connection with the solder with enforced relaxation is between about 1.2 and 1.02.